SFTN6009M-AH

N-Channel Enhancement Mode MOSFET

Features

- AEC-Q101 Qualified
- High-speed switching characteristics
- Low on-resistance
- Halogen and Antimony Free(HAF), RoHS compliant

Gate Source



 Source 2. Source 3. Source 4. Gate
Drain 6. Drain 7. Drain 8. Drain DFN5060 Plastic Package

Application

- AC-DC switching power supply
- DC-DC power converter
- High-voltage H-bridge PWM motor drive

Key Parameters

Parameter	Value	Unit	
BV _{DSS}	60	V	
R _{DS(ON)} Max	16 @ V _{GS} = 10 V	m0	
	20 @ V _{GS} = 4.5 V	mΩ	
V _{GS(th)} typ	1.4	V	
Q _g typ	43 @ V _{GS} = 10 V	nC	

Absolute Maximum Ratings (at Ta = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _G S	V _{GS} ± 20	
Continuous Drain Current $T_c = 25^{\circ}\text{C}$ $T_c = 100^{\circ}\text{C}$	I _D	35 22	А
Peak Drain Current, Pulsed 1)	I _{DM}	120	Α
Single-Pulse Avalanche Current	I _{AS}	19.6	Α
Single-Pulse Avalanche Energy 2)	E _{AS}	19.2	mJ
Power Dissipation T _c = 25°C	P _D	36	W
Operating Junction and Storage Temperature Range	T _j , T _{stg}	- 55 to + 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	Rejc	3.4	°C/W
Thermal Resistance from Junction to Ambient 3)	R _{θJA}	40	°C/W

¹⁾ Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%, Repetitive rating, pulse width limited by junction temperature T_{J(MAX)} = 150°C.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.



 $^{^{2)}}$ Limited by $T_{J(MAX)},$ starting T_J = 25 °C, L = 0.1 mH, R_g = 25 $\Omega,\,I_D$ = 19.6 A, V_{GS} = 10 V.

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Characteristics at Ta = 25°C unless otherwise specified

Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at I _D = 250 μA	BV _{DSS}	60	-	-	V
Drain-Source Leakage Current at V_{DS} = 60 V	I _{DSS}	ı	-	1	μΑ
Gate Leakage Current at $V_{GS} = \pm 20 \text{ V}$	Igss	-	-	± 100	nA
Gate-Source Threshold Voltage at V_{DS} = 10 V, I_D = 250 μA	V _{GS(th)}	1	-	2.5	V
Drain-Source On-State Resistance at V_{GS} = 10 V, I_D = 10 A at V_{GS} = 4.5 V, I_D = 6 A	R _{DS(on)}	1 1	14 -	16 20	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at $V_{DS} = 2 \text{ V}$, $I_D = 10 \text{ A}$	g FS	-	26.8	-	S
Gate resistance at $V_{DS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	R _g	ı	6.9	-	Ω
Input Capacitance at $V_{DS} = 30 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	Ciss	-	2191	-	pF
Output Capacitance at $V_{DS} = 30 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	Coss	-	117	-	pF
Reverse Transfer Capacitance at V_{DS} = 30 V, V_{GS} = 0 V, f = 1 MHz	Crss	-	63	-	pF
Gate Charge Total at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 10 A at V_{DS} = 30 V, V_{GS} = 4.5 V, I_D = 10 A	Q_g	-	43 20	- -	nC
Gate to Source Charge at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 10 A	Q _{gs}	-	7	-	nC
Gate to Drain Charge at V_{DS} = 30 V, V_{GS} = 10 V, I_D = 10 A	Q_{gd}	-	8	-	nC
Turn-On Delay Time at V_{DS} = 30 V, V_{GS} = 10 V, R_G = 6 Ω , I_D = 10 A	t _{d(on)}	-	14	-	ns
Turn-On Rise Time at V_{DS} = 30 V, V_{GS} = 10 V, R_G = 6 Ω , I_D = 10 A	tr	-	25	-	ns
Turn-Off Delay Time at V_{DS} = 30 V, V_{GS} = 10 V, R_G = 6 Ω , I_D = 10 A	t _{d(off)}	-	45	-	ns
Turn-Off Fall Time at V_{DS} = 30 V, V_{GS} = 10 V, R_G = 6 Ω , I_D = 10 A	t _f	-	8	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $I_S = 1 A$, $V_{GS} = 0 V$	V _{SD}	ı	-	1	V
Body-Diode Continuous Current	ls	-	-	35	Α
Body-Diode Continuous Current, Pulsed	Isм	-	-	120	Α
Body Diode Reverse Recovery Time at I _S = 10 A, di/dt = 100 A / µs	t _{rr}	-	15	-	ns
Body Diode Reverse Recovery Charge at I _S = 10 A, di/dt = 100 A / µs	Qrr	-	11	-	nc



Electrical Characteristics Curves

Fig. 1 Typical Output Characteristic

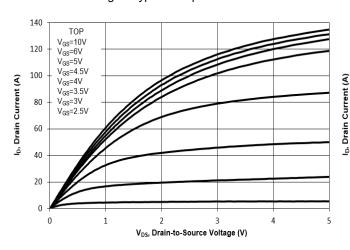


Fig. 2 Typical Transfer Characteristic

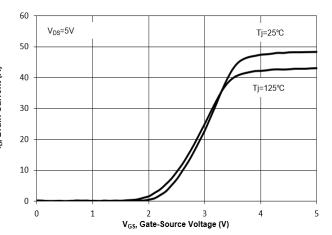


Fig. 3 On-Resistance vs. Drain Current

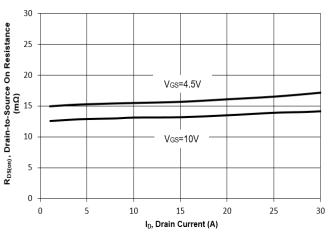


Fig. 4 On-Resistance vs. Gate Voltage

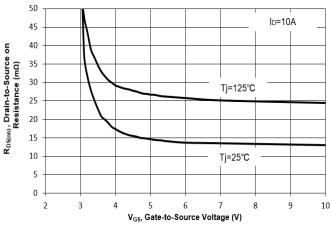


Fig. 5 On-Resistance vs.Tj

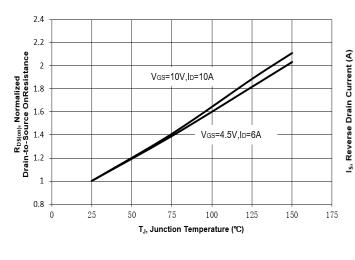
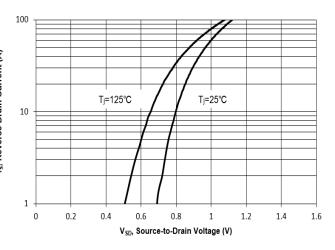


Fig. 6 Typical Body-Diode Forward Characteristic





Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

Fig. 8 Drain-Source Leakage Current vs. Tj

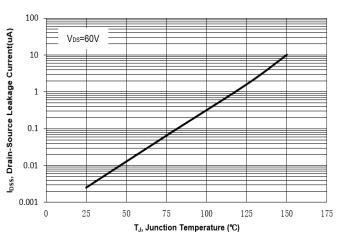


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

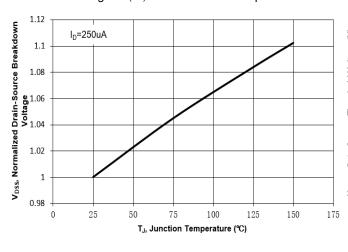


Fig. 10 Gate Threshold Variation vs. T_j

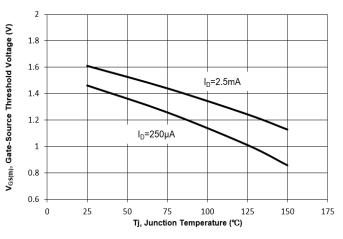
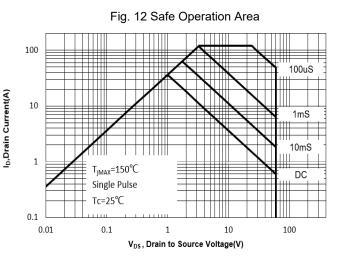


Fig. 11 Gate Charge 10 V_{DS} =30VI_D=10A V_{GS}, Gate-to-Source Voltage(V) 5 3 2 1 0 10 40 50 0 20 30 Q₀, Total Gate Charge(nC)



Electrical Characteristics Curves

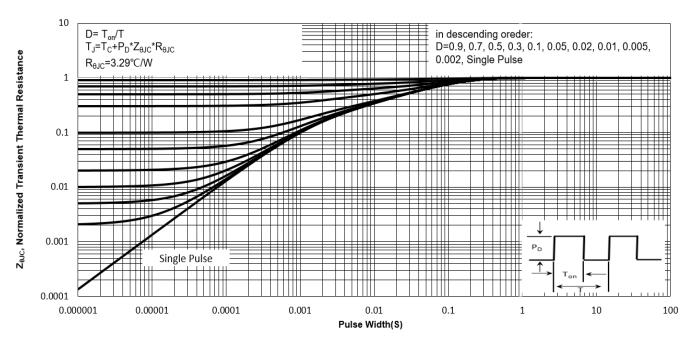
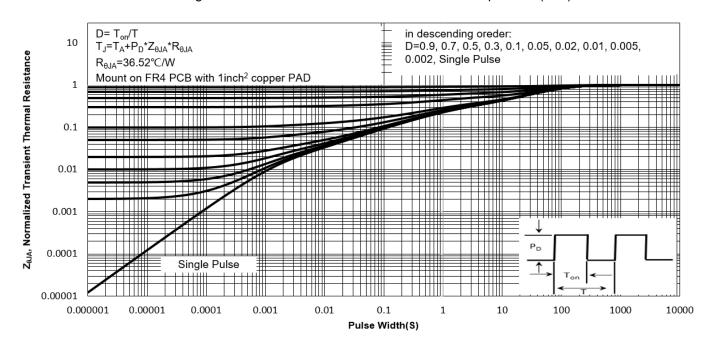


Fig. 13 Normalized Maximum Transient Thermal Impedance(zeuc)

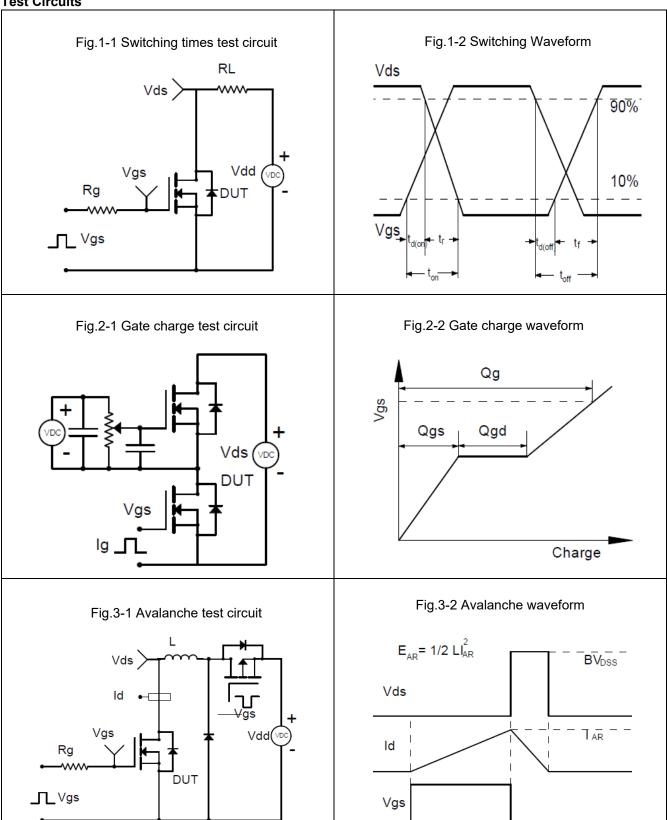






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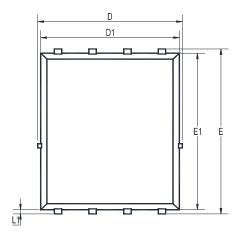
Test Circuits

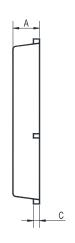


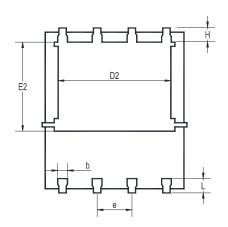


Package Outline Dimensions (Units: mm)

DFN5060

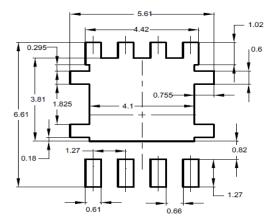






UNIT	Α	b	С	D	D1	D2	E	E1	E2	е	L	L1	Н
	1.12	0.51	0.34	5.26	5.1	4. 5	6.25	6	3.66	1.37	0.71	0.2	0.71
mm	0.9	0.33	0.11	4.7	4.7	3.56	5.75	5.6	3.18	1.17	0.35	0.06	0.35

Recommended Soldering Footprint



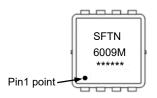
Packing information

Package Tape Width (mm)		Pit	ch	Reel	Size	Des Deel Deelin v Occupit
		mm	inch	mm	inch	Per Reel Packing Quantity
DFN5060	12	8 ± 0.1	0.315 ± 0.004	330	13	5,000

Marking information

- " SFTN6009M " = Part No.
- " ***** " = Date Code Marking

Font type: Arial





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